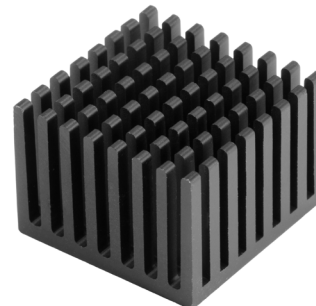


MODEL: HSB11-252518 | DESCRIPTION: HEAT SINK

FEATURES

- BGA design
- top mount
- aluminum alloy
- black anodized finish



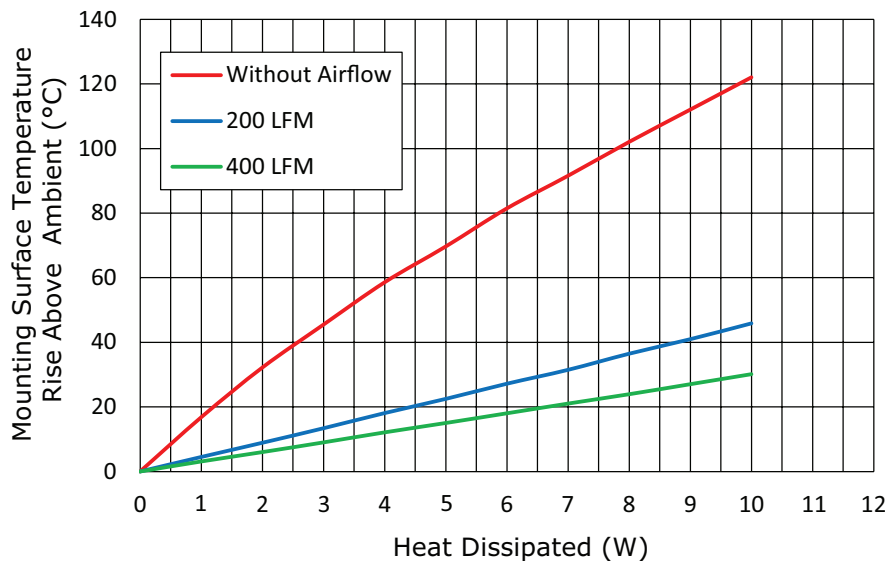
MODEL

MODEL	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSB11-252518	13.70	16.8	4.5	3.1	5.47

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	16.8	4.5	3.1
2	32.2	8.9	6.0
3	45.5	13.4	9.0
4	58.6	18.1	12.1
5	69.7	22.5	15.0
6	81.5	27.2	18.0
7	91.6	31.5	21.0
8	102.1	36.5	23.9
9	112.1	41.0	27.0
10	122.1	45.9	30.1

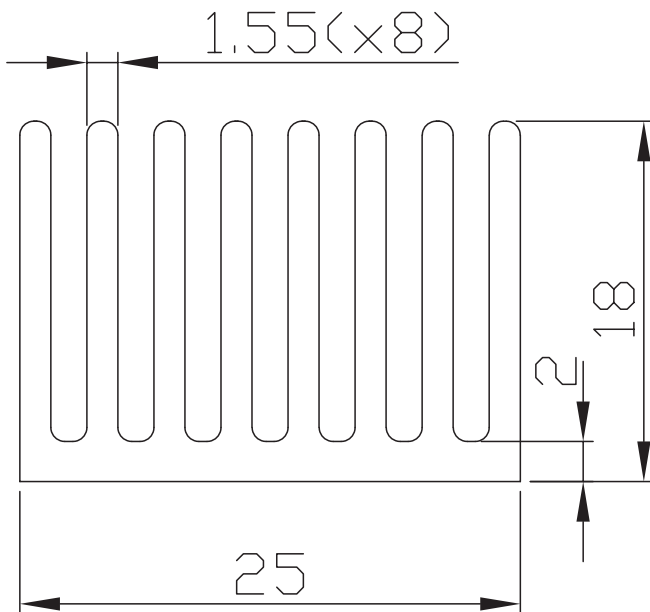
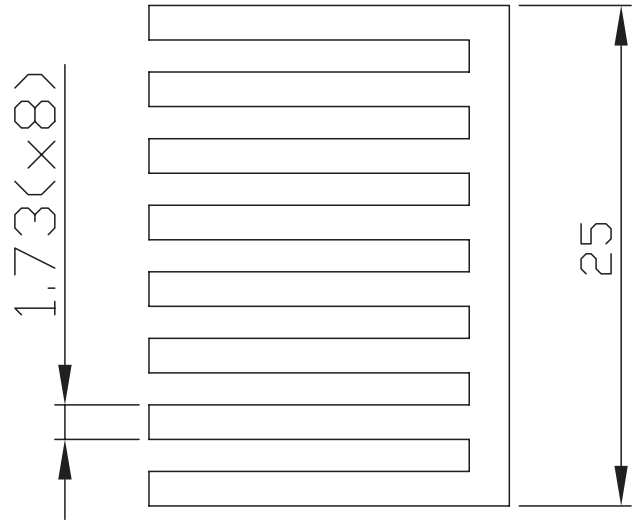
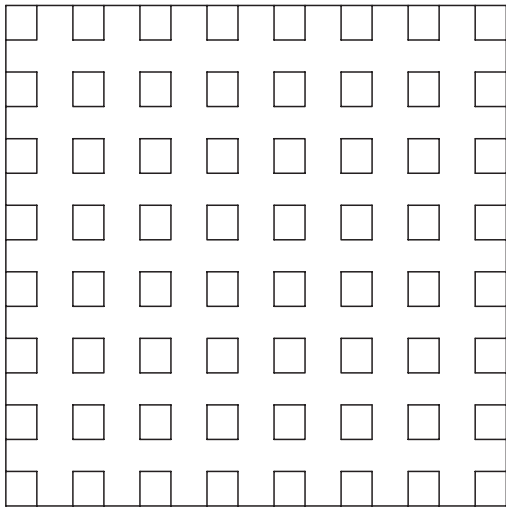


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ± 0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	12.5 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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